



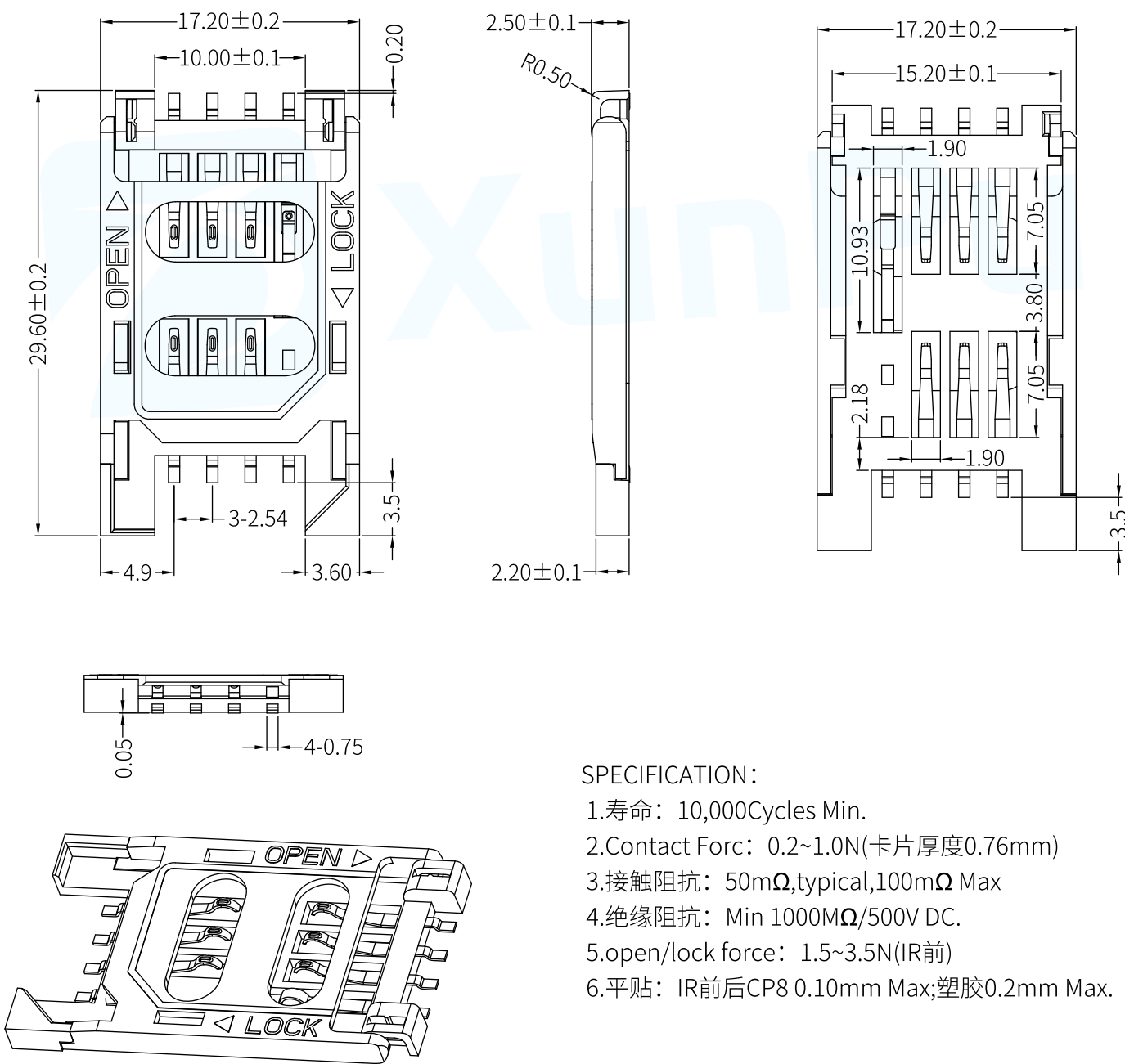
SIM-107B-ARP8
W29.60xD17.20xH2.50

PIN 数(Number of contacts) : 8PIN	耐电压(Withstand voltage) : 500V AC for 1 min
操作方式(Operation mode): 翻盖式/HINGE	操作寿命(Operation life): 5,000 Cycles Min
温度范围(Operating temp): -40°C TO +80°C	焊接温度(Welding temperature): 260±5° 5s
额定负荷(Rated load): 0.5A PER PIN.	焊接方式(Welding mode): 贴片式/SMT
接触电阻(Contact resistance): 100mΩ max.	包装方式(Packaging method): 卷带/Tape & Reel (TR)
绝缘电阻(Insulation resistance): 1000MΩ min.	最小包装(Minimum packing): 1,000/PCS

外形尺寸 (UNIT:MM) / Size Chart

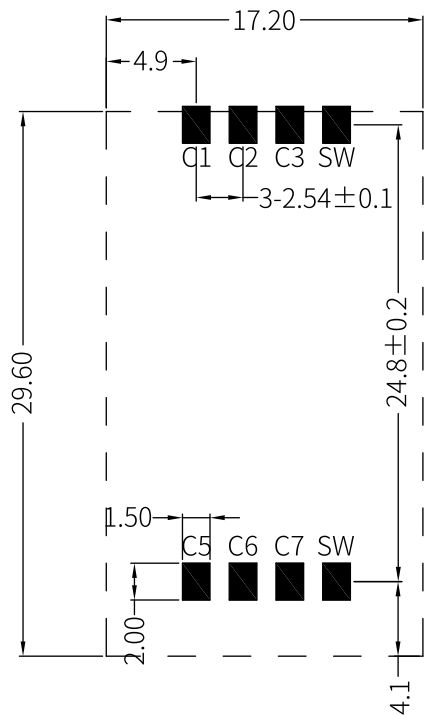
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更多资料请参考技术选型档!

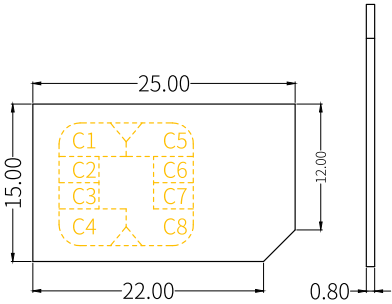


- SPECIFICATION:
- 1.寿命: 10,000Cycles Min.
 - 2.Contact Forc: 0.2~1.0N(卡片厚度0.76mm)
 - 3.接触阻抗: 50mΩ,typical,100mΩ Max
 - 4.绝缘阻抗: Min 1000MΩ/500V DC.
 - 5.open/lock force: 1.5~3.5N(IR前)
 - 6.平贴: IR前后CP8 0.10mm Max;塑胶0.2mm Max.

MINI SIM



RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



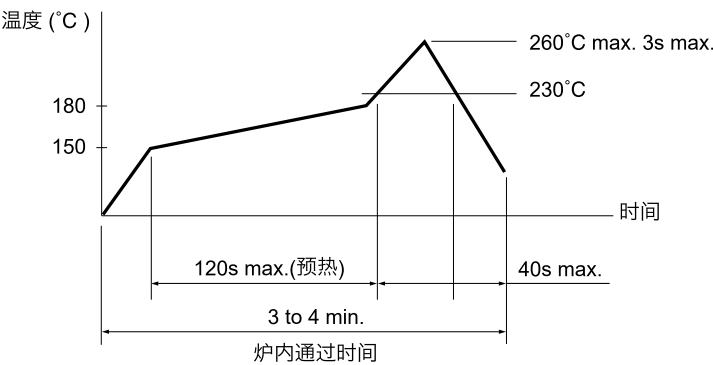
引脚定义/Pin Definition

SIM PIN ASSIGNMENT			
PIN#	NAME	TYPE	DESCRIPTION
C1	供电电压	1	VCC
C2	重置	1	RST
C3	时钟	1	CLK
C5	接地	1	GND
C6	程序电压	1	VPP
C7	输入输出	1	I/O

焊接条件 / Welding conditions

回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
 温度分布/Temperature distribution



手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

注：

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2 的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。